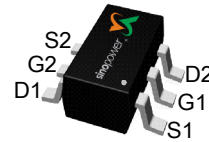


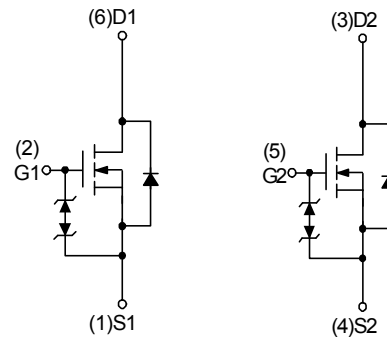
Features

- 30V/0.31A,
 $R_{DS(ON)} = 0.8\Omega(\text{max.}) @ V_{GS} = 10V$
 $R_{DS(ON)} = 1.1\Omega(\text{max.}) @ V_{GS} = 4.5V$
 $R_{DS(ON)} = 2.1\Omega(\text{max.}) @ V_{GS} = 2.5V$
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)
- ESD Protection

Pin Description



Top View of SOT-363

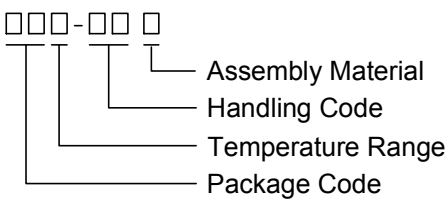


N-Channel MOSFET

Applications

- High Speed and Analog Switching Applications
- Low voltage drive (2.5V drive)

Ordering and Marking Information

<p>SM1600DS □□□-□□□</p> <p>  </p>	<p>Package Code CS : SOT-363</p> <p>Operating Junction Temperature Range C : -55 to 150 °C</p> <p>Handling Code TR : Tape & Reel (3000ea/reel)</p> <p>Assembly Material G : Halogen and Lead Free Device</p>
<p>SM1600DS CS : ● M00X</p>	<p>X - Lot Code</p>

Note : SINOPOWER lead-free products contain molding compounds/die attach materials and 100% matte tin plate termination finish; which are fully compliant with RoHS. SINOPOWER lead-free products meet or exceed the lead-free requirements of IPC/JEDEC J-STD-020D for MSL classification at lead-free peak reflow temperature. SINOPOWER defines "Green" to mean lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

SINOPOWER reserves the right to make changes to improve reliability or manufacturability without notice, and advise customers to obtain the latest version of relevant information to verify before placing orders.

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Unit
Common Ratings			
V_{DSS}	Drain-Source Voltage	30	V
V_{GSS}	Gate-Source Voltage	± 20	
T_J	Maximum Junction Temperature	150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	
I_S	Diode Continuous Forward Current	$T_A=25^\circ\text{C}$ 0.14	A
I_D	Continuous Drain Current	$T_A=25^\circ\text{C}$ 0.31	
		$T_A=70^\circ\text{C}$ 0.25	
I_{DM}^a	Pulsed Drain Current	$T_A=25^\circ\text{C}$ 0.4	
P_D	Maximum Power Dissipation	$T_A=25^\circ\text{C}$ 0.16	W
		$T_A=70^\circ\text{C}$ 0.1	
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	Steady State 800	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance-Junction to Case	760	$^\circ\text{C/W}$

Note a : Max. current is limited by bonding wire.

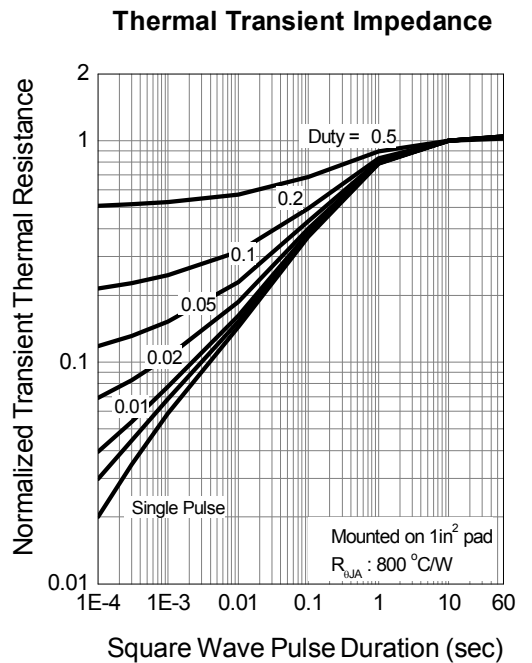
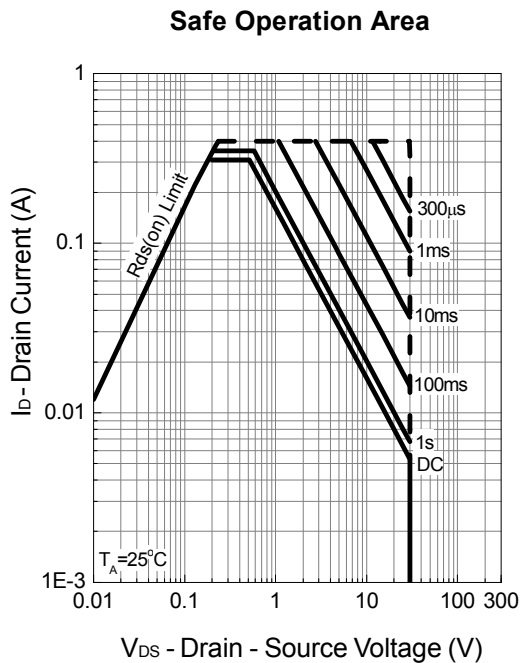
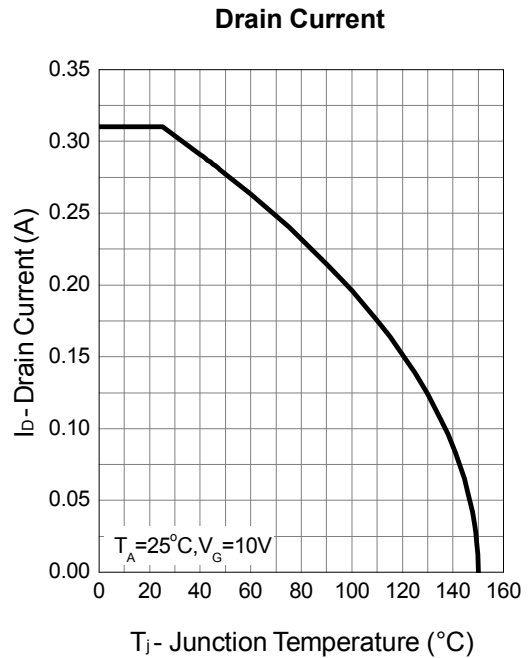
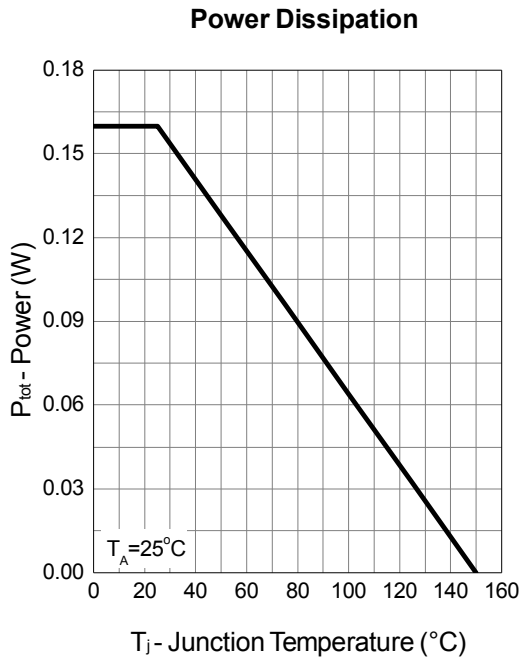
Electrical Characteristics (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =24V, V _{GS} =0V T _J =85°C	-	-	1 30	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250μA	0.7	1.1	1.5	V
I _{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	-	±2	±9	μA
R _{DS(ON)} ^b	Drain-Source On-state Resistance	V _{GS} =10V, I _{DS} =0.4A V _{GS} =4.5V, I _{DS} =0.3A V _{GS} =4V, I _{DS} =0.3A V _{GS} =2.5V, I _{DS} =0.2A	-	0.5 0.8 0.9 1.4	0.8 1.1 -	Ω
G _{fs}	Forward Transconductance	V _{DS} =3, I _D =10mA	-	0.9	-	S
Diode Characteristics						
V _{SD} ^b	Diode Forward Voltage	I _{SD} =0.4A, V _{GS} =0V	-	0.85	1.1	V
Dynamic Characteristics^c						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =15V, Frequency=1.0MHz	-	23	-	pF
C _{oss}	Output Capacitance		-	5	-	
C _{riss}	Reverse Transfer Capacitance		-	2	-	
t _{d(ON)}	Turn-on Delay Time	V _{DD} =10V, R _L =10Ω, I _{DS} =1A, V _{GEN} =10V, R _G =6Ω	-	1.4	-	ns
t _r	Turn-on Rise Time		-	11.8	-	
t _{d(OFF)}	Turn-off Delay Time		-	8	-	
t _f	Turn-off Fall Time		-	2	-	
Gate Charge Characteristics^c						
Q _g	Total Gate Charge	V _{DS} =15V, V _{GS} =10V, I _{DS} =1A	-	1.6	-	nC
Q _g	Total Gate Charge	V _{DS} =15V, V _{GS} =4.5V, I _{DS} =1A	-	0.7	-	
Q _{gs}	Gate-Source Charge		-	0.54	-	
Q _{gd}	Gate-Drain Charge		-	0.03	-	
Q _{gth}	Threshold Gate Charge		-	0.02	-	

Note b : Pulse test; pulse width ≤ 300μs, duty cycle ≤ 2%.

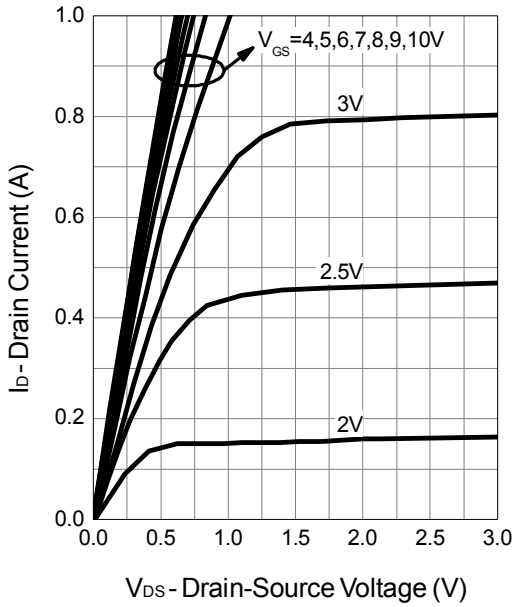
Note c : Guaranteed by design, not subject to production testing.

Typical Operating Characteristics

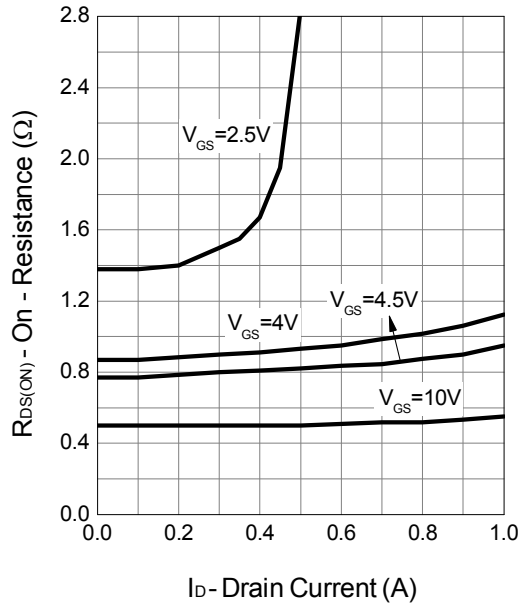


Typical Operating Characteristics (Cont.)

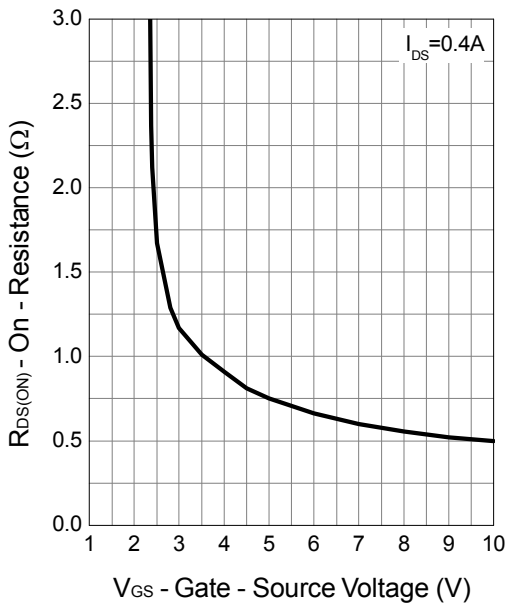
Output Characteristics



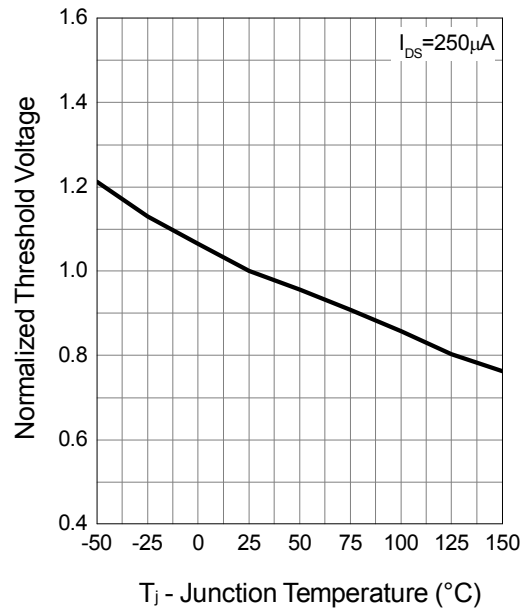
Drain-Source On Resistance



Gate-Source On Resistance

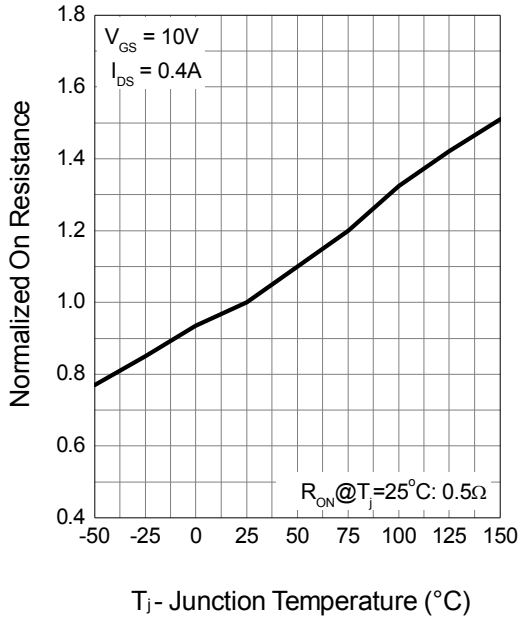


Gate Threshold Voltage

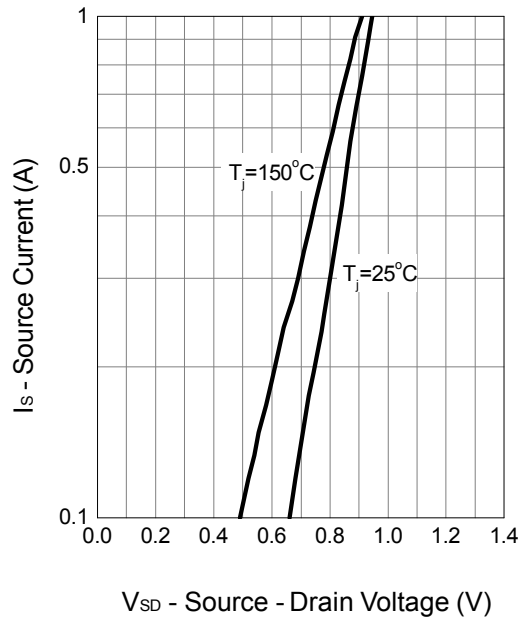


Typical Operating Characteristics (Cont.)

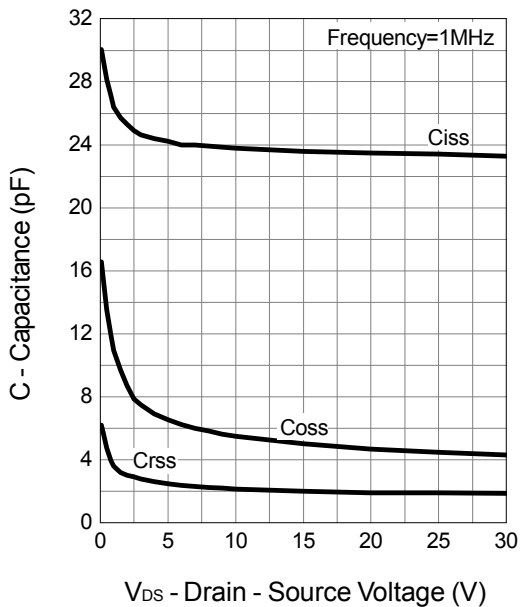
Drain-Source On Resistance



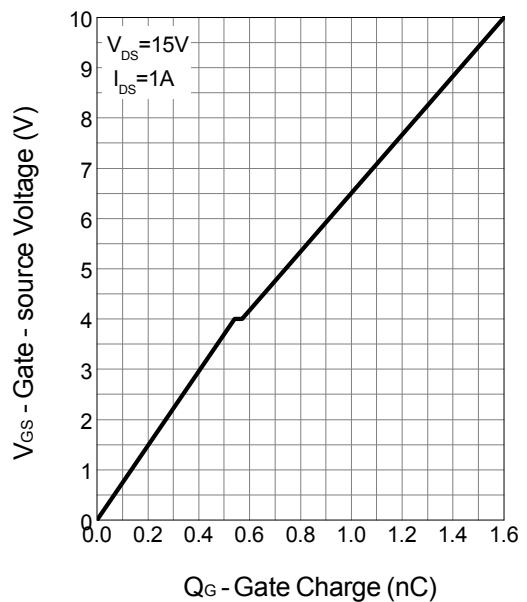
Source-Drain Diode Forward



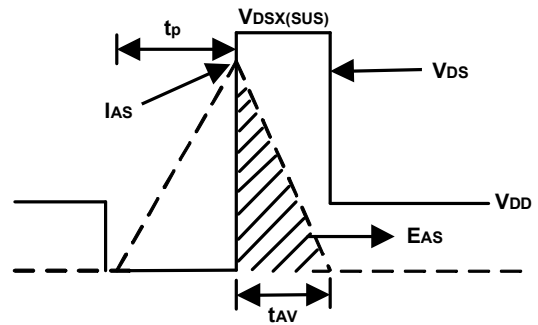
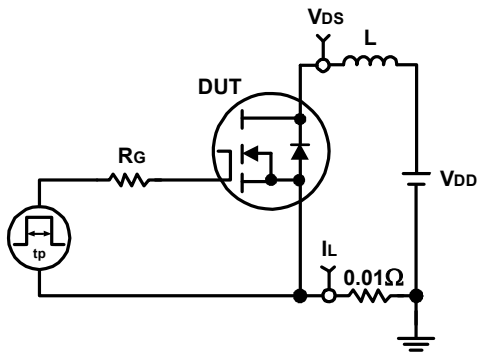
Capacitance



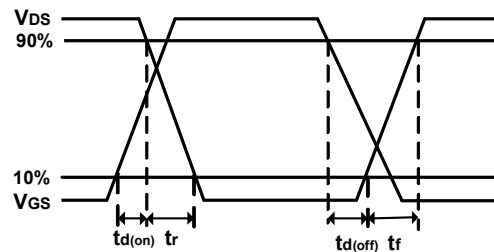
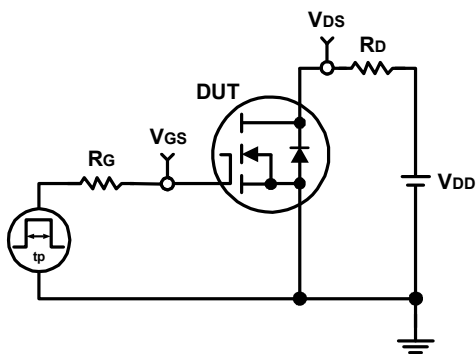
Gate Charge



Avalanche Test Circuit and Waveforms

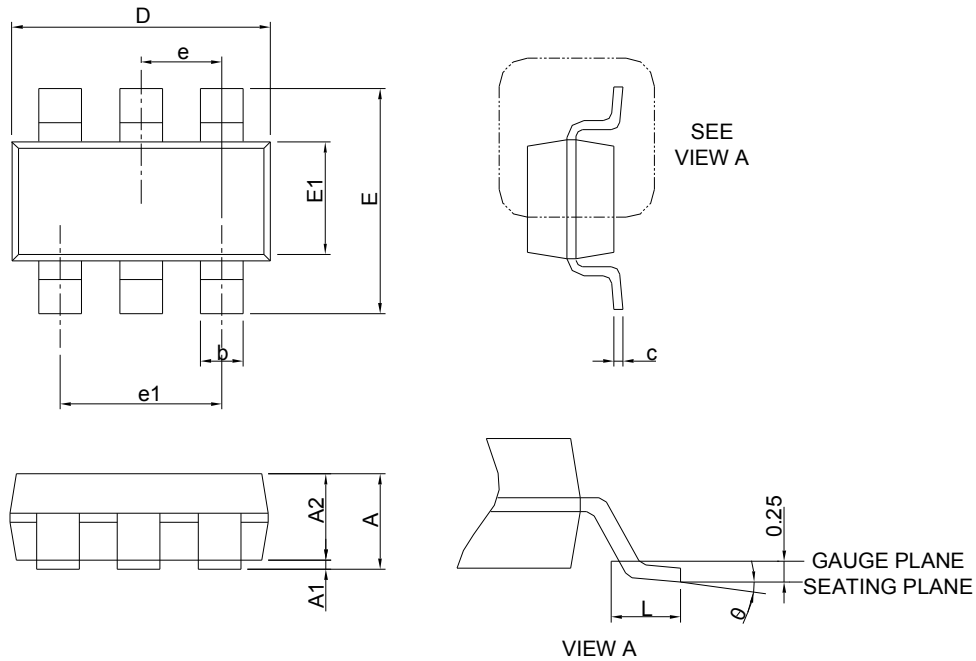


Switching Time Test Circuit and Waveforms



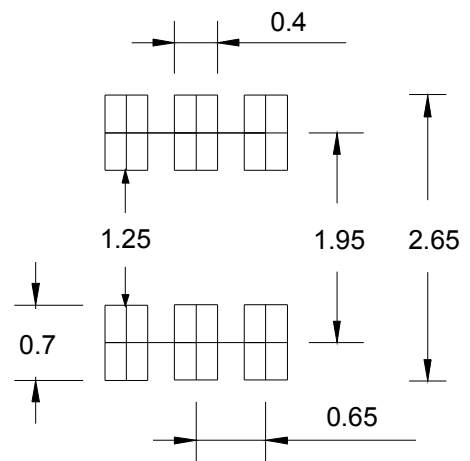
Package Information

SOT-363



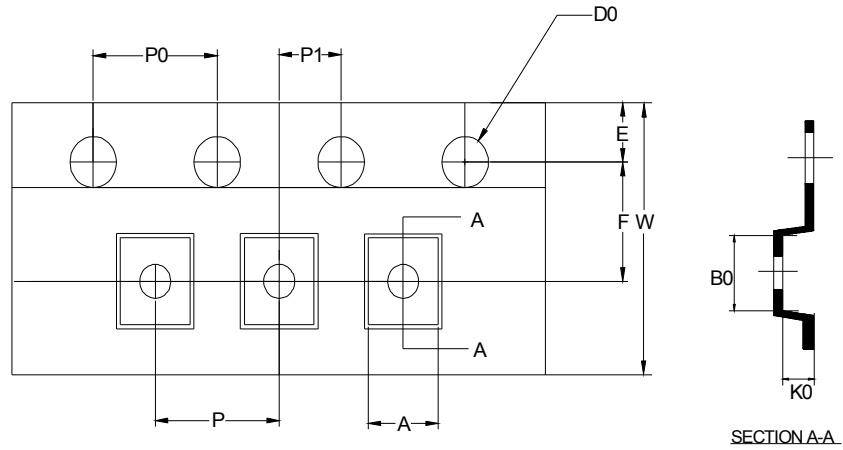
DIMENSIONS	SOT-363			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	-	1.25	-	0.049
A1	0.00	0.15	0.000	0.006
A2	0.90	1.30	0.035	0.051
b	0.15	0.35	0.006	0.014
c	0.08	0.15	0.003	0.006
D	2.00	2.20	0.079	0.087
E	2.15	2.45	0.085	0.096
E1	1.15	1.35	0.045	0.053
e	0.65 BSC		0.026 BSC	
e1	1.30 BSC		0.051 BSC	
L	0.26	0.46	0.01	0.018
θ	0°	8°	0°	8°

RECOMMENDED LAND PATTERN



UNIT: mm

Carrier Tape & Reel Dimensions

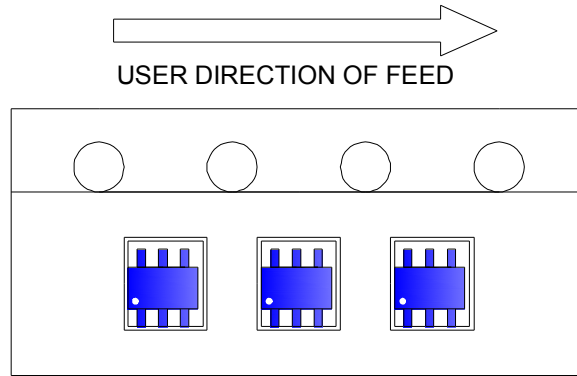


Application	A	H	T1	C	d	D	W	E
SOT-363	178.0±2.00	50 MIN.	8.4+2.00 -0.00	13.0+0.50 -0.20	1.5 MIN.	20.2 MIN.	8.0±0.30	1.75±0.10
	F	P0	P1	P	D0	A0	B0	K0
	3.5±0.05	4.0±0.10	2.0±0.10	4.0±0.1	1.5+0.10	2.25±0.10	2.55±0.10	1.20±0.20

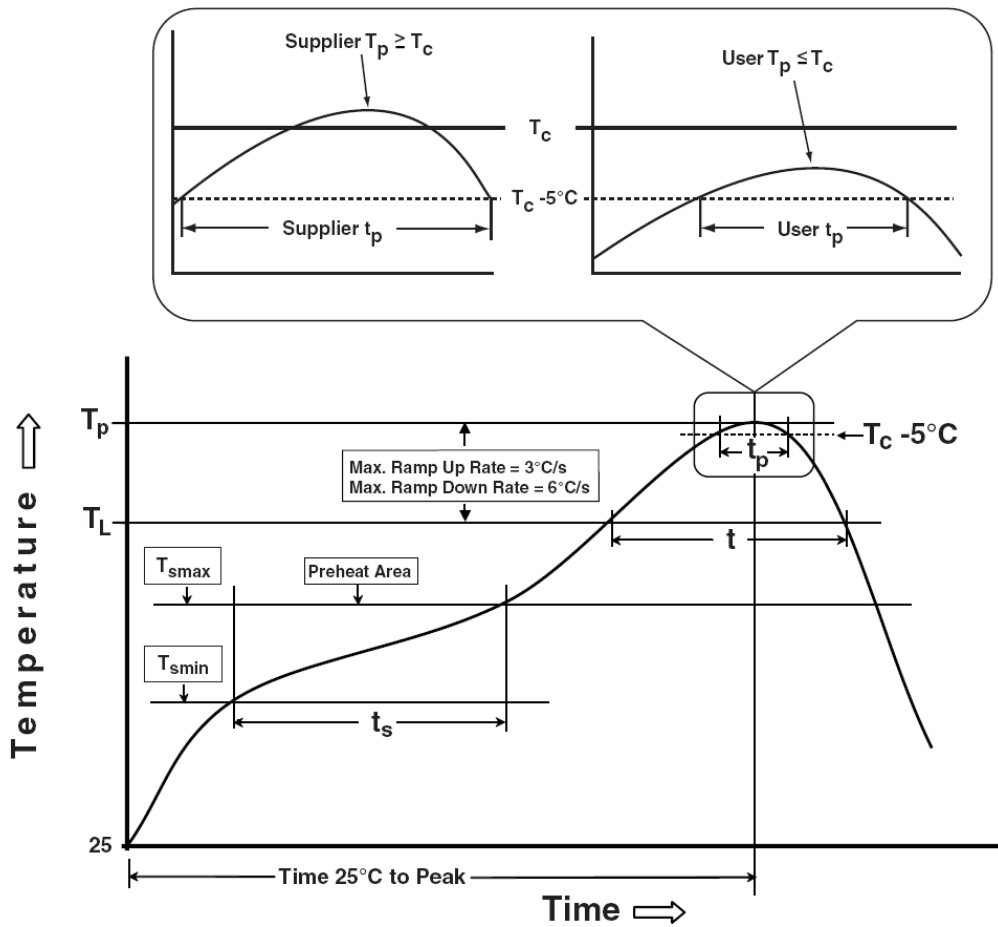
(mm)

Taping Direction Information

SOT-363



Classification Profile



Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat & Soak		
Temperature min (T_{smin})	100 °C	150 °C
Temperature max (T_{smax})	150 °C	200 °C
Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds	60-120 seconds
Average ramp-up rate (T_{smax} to T_p)	3 °C/second max.	3°C/second max.
Liquidous temperature (T_L)	183 °C	217 °C
Time at liquidous (t_L)	60-150 seconds	60-150 seconds
Peak package body Temperature (T_p)*	See Classification Temp in table 1	See Classification Temp in table 2
Time (t_p)** within 5°C of the specified classification temperature (T_c)	20** seconds	30** seconds
Average ramp-down rate (T_p to T_{smax})	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.
* Tolerance for peak profile Temperature (T_p) is defined as a supplier minimum and a user maximum.		
** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.		

Table 1. SnPb Eutectic Process – Classification Temperatures (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

Reliability Test Program

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HTRB	JESD-22, A108	1000 Hrs, 80% of VDS max @ T_{jmax}
HTGB	JESD-22, A108	1000 Hrs, 100% of VGS max @ T_{jmax}
PCT	JESD-22, A102	168 Hrs, 100%RH, 2atm, 121°C
TCT	JESD-22, A104	500 Cycles, -65°C~150°C

Customer Service

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